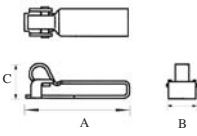
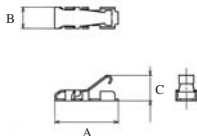
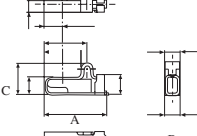
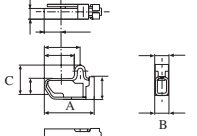


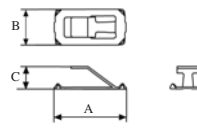
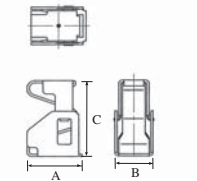
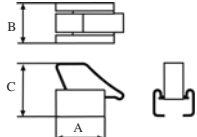
Features

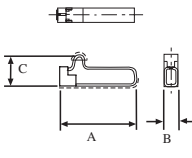
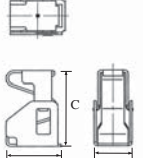
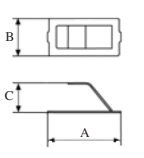
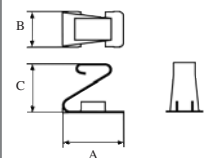
- Contact components enable automatic mounting. Contact components enhance grounding effect around PCBs (printed circuit boards).
- Supplied with the enboss tape for autoinsertion assembly.
- Height 1.0mm- 7.0 mm are available.
- Improved spring form.

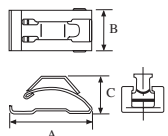
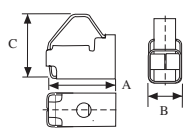
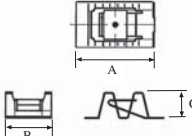
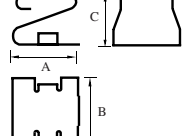


	OG-300810	OG-301012	OG-320816	OG-321022
A	3.0	3.0	3.2	3.2
B	0.8	1.0	0.8	1.0
C	1.0	1.2	1.6	2.2
Metal Thickness	0.08	0.08	0.12	0.12
Material	Phosphor Bronze	Phosphor Bronze	Phosphor Bronze	Phosphor Bronze
Surface treatment	Sn reflow plating on the underplating by Ni	Surface Partly Alu plating on the underplating Ni	Partly Au plating on the underplating by Ni	Partly Au plating on the underplating by Ni
Packing Quantity	4000	8000	8000	7000
Dimensions				

More technical data upon request

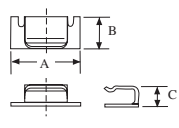
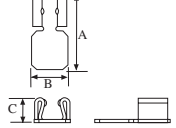
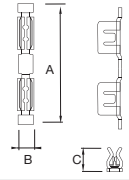
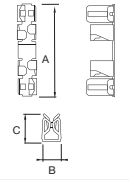
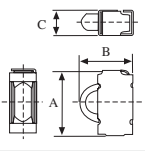
	OG-321610G		OG-362550	OG-363040 OG-363050
A	3.2		3.6	3.6
B	1.6		2.5	3
C	1		5.0	4.0 (OG-363040) 5.0 (OG-363050)
Metal Thickness	0.08		0.15	0.1
Material	Stainless steel		Phosphor Bronze	BeCu
Surface treatment	Partly Au plating on the underplating by Ni		Sn reflow plating	Ni plating Partly Sn plating on the underplating by Ni
Packing Quantity	3000		1000	8000
Dimensions				

	OG-450818	OG-453060 OG-453070	OG-502620R	OG-503040
A	4.5	4.5	5	5
B	0.8	3.0	2.6	3
C	1.8	6.0 (OG-453060) 7.0 (OG-453070)	2	4
Metal Thickness	0.12	0.22	0.08	0.1
Material	BeCu	Phosphor Bronze	Stainless steel	BeCu
Surface treatment	Partly Au plating on the underplating by Ni	Sn reflow plating	Partly Au plating on the underplating by Ni	Sn plating
Packing Quantity	8000	1500	2000	1000
Dimensions				

	OG-542925	OG-603060 OG-603070	OG-865028	OG-909068
A	5.4	6.0	8.6	9.0
B	2.9	3.0	5.0	9.0
C	2.5	6.0 (OG-603060) 7.0 (OG-603070)	2.8	6.8
Metal Thickness	0.12	0.12 (OG-603060) 0.08 (OG-603070)	0.08	0.15
Material	Phosphor Bronze	Phosphor Bronze	Phosphor Bronze	Phosphor Bronze
Surface treatment	Partly Au plating on the underplating by Ni	Sn plating	Sn plating	Sn reflow plating on the underplating by Ni
Packing Quantity	5000	850 (OG-603060) 750 (OG-603070)	3000	1000
Dimensions				

GROUNDING

ON BOARD CLAMP/ON BOARD CLIP / ON BOARD SIDE CONTACT

	OGC-331610 OGC-331612	OGC-311510U	OGCP-650813*	OGCP-1182435	OGSC-756030
A	3.3	3.1	6.7	11.8	7.5
B	1.6	1.5	0.8	2.4	6.0
C	1.05(OGC-331610) 1.15(OGC-331612)	1.02	1.28	3.5	3
Metal Thickness	0.15	0.12	0.15	0.2	0.12
Material	Phosphor Bronze	Phosphor Bronze	Titanium copper	Phosphor Bronze	Phosphor Bronze
Surface treatment	Sn plating	Sn plating	Sn plating	Sn reflow plating on Cu plating	Sn plating
Packing Quantity	3000	3000	8000	3000	2000
Dimensions					

*with Gold plating available (with suffix "G")
(Dimension in mm)

ON-BOARD CONTACT ENGINEERING KIT OG-K01/OG-K02T.



On-board contact engineering Kit OG-K01.
Various on-board contacts in a compact case.

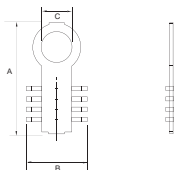
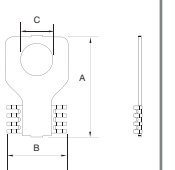
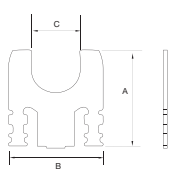
OG-K01 (OG series)
OG-K02T (TOG series)

ON-BOARD LUG TERMINAL

Features

- To be able to avoid the solder flux problem
- FG terminal to be soldered on the PCB
- Supplied with enboss tape for automatic chip mounter machine
- Diameter of screw bolt shall be $\square 2.6\text{mm}$ and $\square 3.0\text{ mm}$

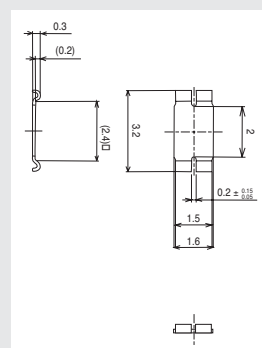


	OG-R26-SN	OG-R30-SN	OG-RM30HF
A	10.7	12.7	8
B	6	8	7.6
C	3	4	4
Metal Thickness	0.3	0.3	0.3
Material	Tough Pitch copper		Tough Pitch copper
Surface treatment	Pb-Sn Plating on Cu plating		Sn plating on Ni plating
Packing Quantity	2000	2000	3000
Dimensions			

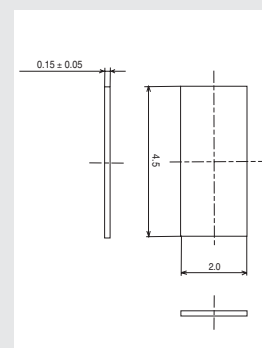
(Dimension in mm)

ON-BOARD PLATE

	OGP-3216	OGP-4520
Metal Thickness	0.1	0.15
Material	Brass	Brass
Surface treatment	Au/Ni plating	Sn plating on the underplating by Cu
Packing Quantity	4000	3000



OGP-3216



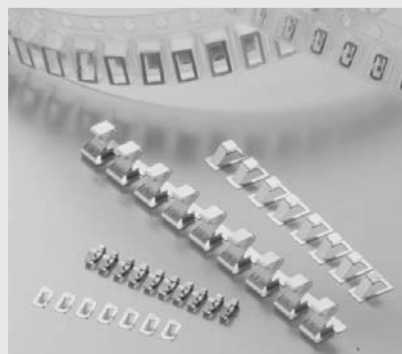
OGP-4520

GROUNDING

ON-BOARD CONTACTS

Features

- Contact components enable automatic mounting.
- Contact components enhance grounding effect around PCBs (printed circuit boards).
- Supplied with the enboss tape for autoinsertion assembly.
- Improved spring form.



Dimension in mm

Height: 2.0 - 6.2 mm are available
 Material: 0.08 mm Beryllium Copper
 Gold plating on Nickel underplating

Nickel (μm)	Au (μm)
3.05	0.03

Description		TOG-20-30-25	TOG-20-45-45	TOG-25-40-41	
W		2.00	2.00	2.50	
T		3.00	4.50	4.00	
Original Height	H	2.50	4.50	4.10	
Final height(mm)- (after compression)	Min	1.70	3.00	3.80	
	Max	2.25	4.00	2.60	
Compression Ratio(final/original)		68%~90%	67%~89%	63%~93%	
Packing Quantity		6000	3000	2000	
Dimensions					

Description		TOG-25-70-90	TOG-20-70-62	TOG-40-40-51	
W		2.50	2.00	4.00	
T		7.00	7.00	4.00	
Original Height	H	9.00	6.20	5.10	
Final height(mm)- after compression	Min	6.48	3.50	3.10	
	Max	8.90	5.50	4.60	
Compression Ratio(final/original)		72%~99%	56%~89%	61%~90%	
Packing Quantity		800	1200	1500	
Dimensions		